





SLF65R280E7C / SLP65R280E7C 650V N-Channel Multi-EPI Super-JMOSFET

General Description

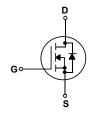
This Power MOSFET is produced using Msemitek's advanced Superjunction MOSFET technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies.

Features

- 15A,650V@ $T_{J,max}$, $R_{DS(on)Typ}$ =238m Ω @ V_{GS} = 10V
- Low gate charge(typ. Qg =21.0nC)
- High ruggedness
- Ultra fast switching
- 100% avalanche tested
- Improved dv/dt capability







Absolute Maximum Ratings

T_C = 25°C unless otherwise noted

Symbol	Parameter		SLF65R280E7C /	SLP65R280E7C	Units
V_{DSS}	Drain-Source Voltage		650		V
	Drain Current * - Continuous (T _C = 25°C)		15	5	Α
ID	- Continuous (T _C = 100°C)		8.0	0	Α
I _{DM}	Drain Current * - Pulsed	(Note 1)	37.	5	Α
V _{GSS}	Gate-Source Voltage		±3	0	V
EAS	Single Pulsed Avalanche Energy	(Note 2)	54		mJ
I _{AR}	Avalanche Current	(Note 1)	3.0		Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	1.11		mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	20)	V/ns
av/at	MOSFET dv/dt		100		V/115
В	Power Dissipation (T _C = 25°C)		30	100	W
P _D	- Derate above 25°C		0.24	8.0	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150		°C
TL	Maximum lead temperature for soldering purpo	ses,	26	0	သိ
	1/8" from case for 5 seconds				

^{*} Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	SLF65R280E7C / SLP65R280E7C		Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	4.1	1.25	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	-	°C/W

Package Marking

Symbol

Part Number	Top Marking	Package	Packing Method	MOQ	QTY
SLF65R280E7C	SLF65R280E7C	TO-220F	Tube	1000	5000
SLP65R280E7C	SLP65R280E7C	TO-220C	Tube	1000	5000

Electrical Characteristics

Parameter

T_C = 25°C unless otherwise noted

Test Conditions

Min

Тур

Max

Units

Off Ch	Off Characteristics								
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 1mA	650			٧			
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_{D} = 1\text{mA,}$ $T_{J} = 150^{\circ}\text{C}$	700		-	V			
1	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V			1.0	uA			
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =520 V, T _C = 125°C		2.0		uA			
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA			
Igssr	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA			

On Characteristics

$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250uA$	2.5		4.5	V	l
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 5.3A		238	280	mΩ	l

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0 V, f = 250KHz	1	789		pF
Coss	Output Capacitance		1	22	-	pF
C_{rss}	Reverse Transfer Capacitance	1 2001(1)2				pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time		-	11	-	ns
t _r	Turn-On Rise Time	$V_{DS} = 400 \text{ V}, I_{D} = 5.3 \text{A},$	-	10	-	ns
$t_{d(off)}$	Turn-Off Delay Time	$R_G = 10\Omega, VGS = 10 V$ (Note 4, 5)	1	49	-	ns
t _f	Turn-Off Fall Time	(11010 1, 0)	-	10	-	ns
Q_g	Total Gate Charge	$V_{DS} = 400 \text{ V}, I_{D} = 5.3 \text{ A},$	-	21.0	-	nC
Qgs	Gate-Source Charge	V _{GS} = 10 V	-	4.0	-	nC
Q_{gd}	Gate-Drain Charge	(Note 4, 5)	1	10.9	-	nC
R_{G}	Gate Resistance	f = 1MHz		6.9		Ω

Drain-Source Diode Characteristics and Maximum Ratings

ls	Maximum Continuous Drain-Source Diode Forward Current		-		12.5	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		-	-	37.5	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S =5.3A	1	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{DD} = 400 V, I _S =5.3A,	1	240	-	ns
Qrr	Reverse Recovery Charge	dI _F / dt = 100 A/us (Note 4)		2.36		uC

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} =3A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25°C 3. I_{SD} ≤ 5.3A, di/dt ≤ 100A/us, V_{DD} ≤400, Starting T_J = 25°C
- 4. Pulse Test : Pulse width \leq 300us, Duty cycle \leq 2%
- 5. Essentially independent of operating temperature

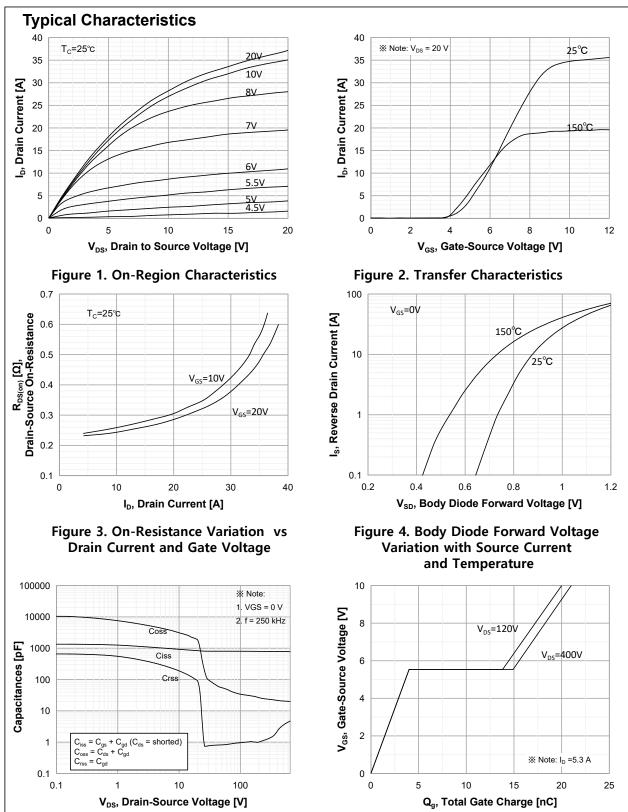
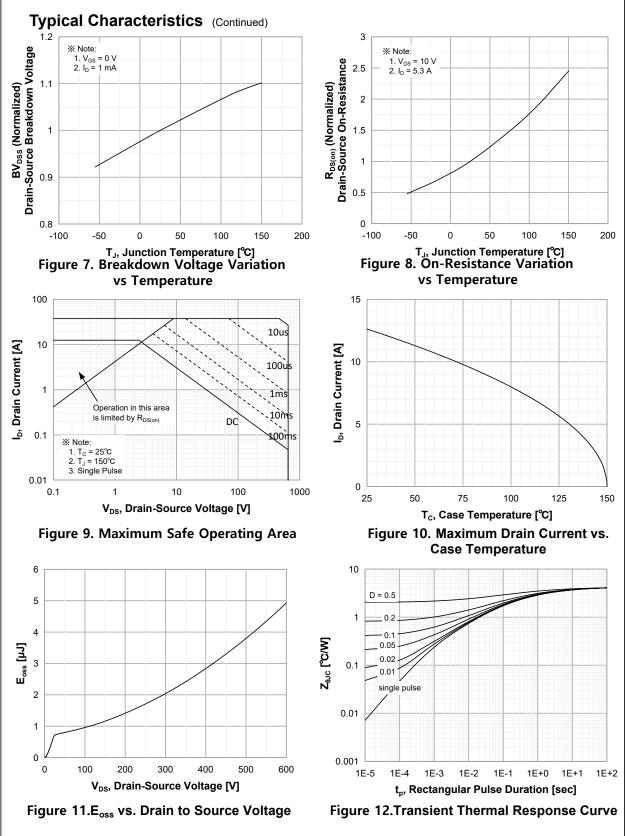
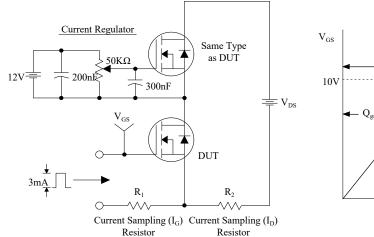


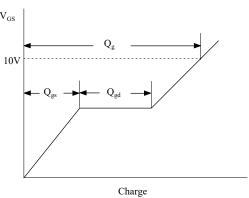
Figure 5. Capacitance Characteristics

Figure 6. Gate Charge Characteristics

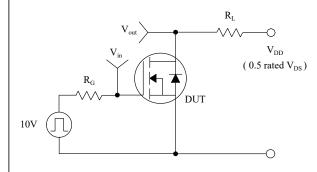


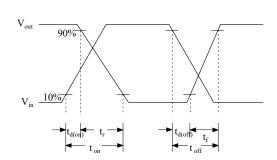
Gate Charge Test Circuit & Waveform



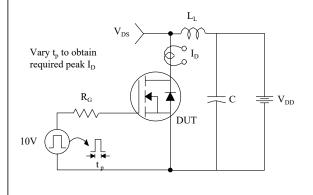


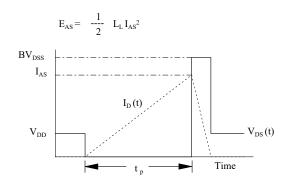
Resistive Switching Test Circuit & Waveforms



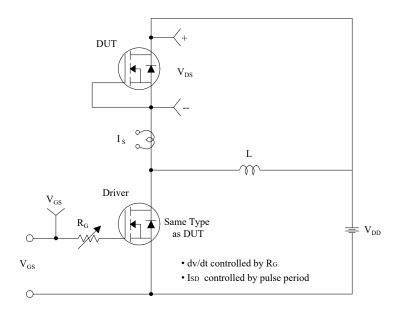


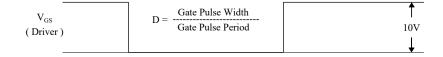
Unclamped Inductive Switching Test Circuit & Waveforms

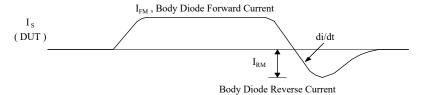


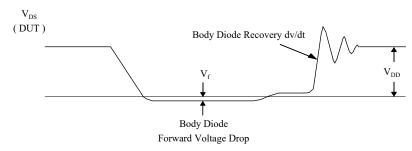


Peak Diode Recovery dv/dt Test Circuit & Waveforms









TO-220F OUTLINE 4.70±0.2 10.16±0.2 2.54±0.2 Φ 3. 18 ± 0. 2 \bigoplus 6.68±0.3 57 ± 0 . 5 12. 2.76 ± 0.2 3 ± 0.2 0.8 ± 0.2 $95\pm0.$

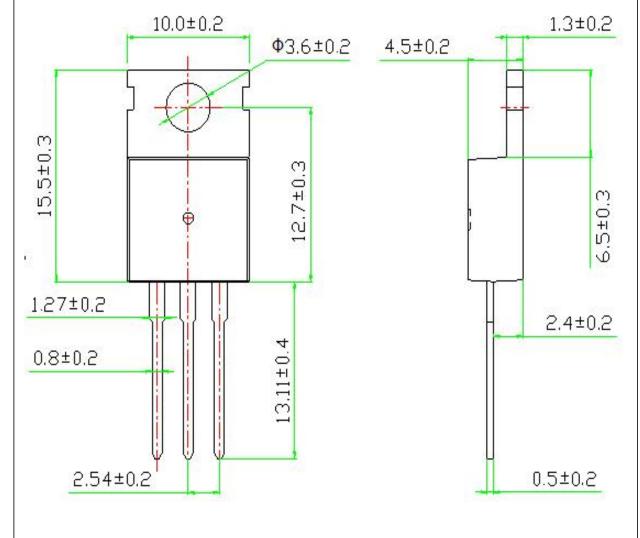
NOTE:

1The plastic package is not marked as smooth surfaceRa=0.1;Subglossy surfaceRa=0.8 2.Undeclared tolerance \pm 0.15,Unmarked filletRmax=0.25

 2.54 ± 0.2

 0.5 ± 0.1

TO-220C OUTLINE



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